

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
19 August 2004 (19.08.2004)

PCT

(10) International Publication Number
WO 2004/070790 A3

(51) International Patent Classification⁷: **H01L 21/44**,
21/48, 21/50, 23/10, 23/34, 23/48, 23/52, 29/40

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(21) International Application Number:
PCT/US2004/002985

(22) International Filing Date: 3 February 2004 (03.02.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/444,205 3 February 2003 (03.02.2003) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,
ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),
Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), Euro-
pean (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR,
GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
ML, MR, NE, SN, TD, TG).

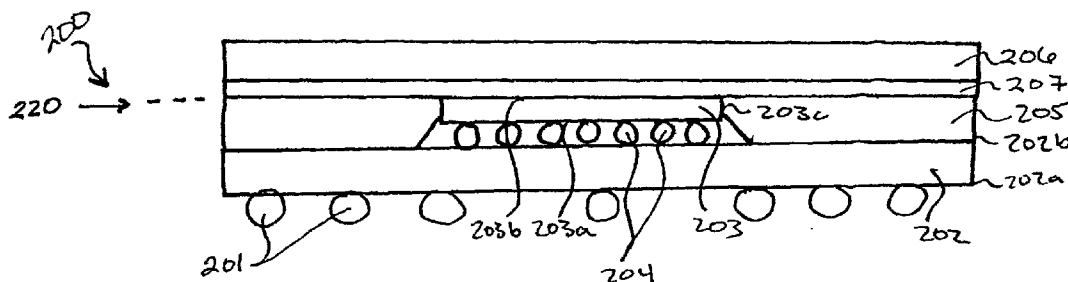
Published:

- with international search report
- before the expiration of the time limit for amending the
claims and to be republished in the event of receipt of
amendments

(88) Date of publication of the international search report:
18 November 2004

[Continued on next page]

(54) Title: MOLDED HIGH DENSITY ELECTRONIC PACKAGING STRUCTURE FOR HIGH PERFORMANCE APPLICATIONS



(57) Abstract: The invention discloses a thermally enhanced ball grid array package (200) including a base layer element (202) and a flip chip die (203) mounted on the base layer element (202). The die (203) has a first surface (203a) electrically coupled to the base layer element (202), a second surface (203b) opposite to the first surface (203a), and lateral sides (203c). A molding compound (205) encapsulates the base layer element (202) and the lateral sides (203c) of the die (203). A surface (220) is formed of the second surface (203b) of the die (203) and an upper surface of the molding compound. A material (207) is disposed on the surface (220), and a heat spreader (206) is mounted on the material.

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